To all our customers

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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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   Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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2SC4499(L)/(S)

Silicon NPN Triple Diffused

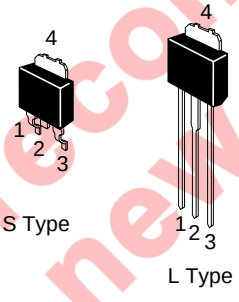
ADE-208-893 (Z)
1st. Edition
September 2000

Application

High speed and high voltage switching

Outline

DPAK



1. Base
2. Collector
3. Emitter
4. Collector

Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings	Unit
Collector to base voltage	V_{CBO}	500	V
Collector to emitter voltage	V_{CEO}	400	V
Emitter to base voltage	V_{EBO}	10	V
Collector current	I_C	0.5	A
Collector peak current	$I_{C(peak)}$	1.0	A
Collector power dissipation	P_C	0.75	W
	P_C*[1]	10	
Junction temperature	Tj	150	°C
Storage temperature	Tstg	–55 to +150	°C

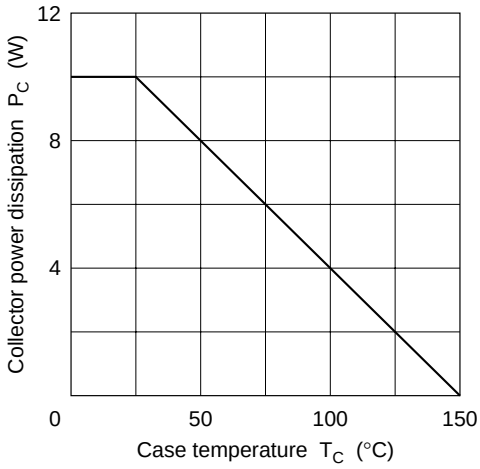
Note: 1. Value at T_C = 25°C.

Electrical Characteristics (Ta = 25°C)

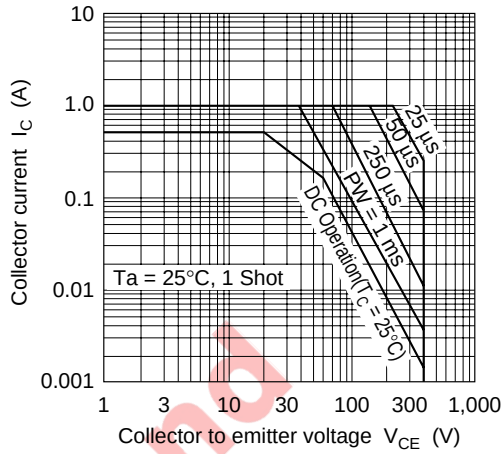
Item	Symbol	Min	Typ	Max	Unit	Test conditions
Collector to emitter sustain voltage	$V_{CEO(sus)}$	400	—	—	V	I_C = 0.1 A, R_{BE} = ∞ L = 100 mH
Emitter to base breakdown voltage	$V_{(BR)EBO}$	10	—	—	V	I_E = 10 mA, I_C = 0
Collector cutoff current	I_{CBO}	—	—	20	µA	V_{CB} = 400 V, I_E = 0
	I_{CEO}	—	—	50		V_{CE} = 350 V, R_{BE} = ∞
DC current transfer ratio	h_{FE1}	12	—	—		V_{CE} = 5 V, I_C = 0.25 A*[1]
	h_{FE2}	5	—	—		V_{CE} = 5 V, I_C = 0.5 A*[1]
Collector to emitter saturation voltage	$V_{CE(sat)}$	—	—	1.0	V	I_C = 0.25 A, I_B = 0.05 A*[1]
Base to emitter saturation voltage	$V_{BE(sat)}$	—	—	1.5	V	I_C = 0.25 A, I_B = 0.05 A*[1]
Turn on time	t_{on}	—	—	1.0	µs	I_C = 0.5 A, I_{B1} = $-I_{B2}$ = 0.1 A,
Storage time	t_{stg}	—	—	2.0	µs	V_{CC} ≅ 150 V
Fall time	t_f	—	—	1.0	µs	

Note: 1. Pulse test.

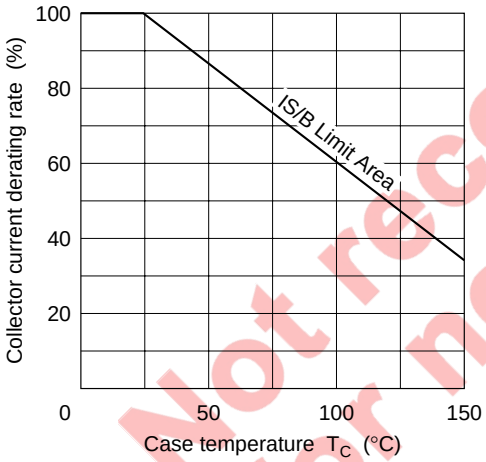
Maximum Collector Dissipation Curve



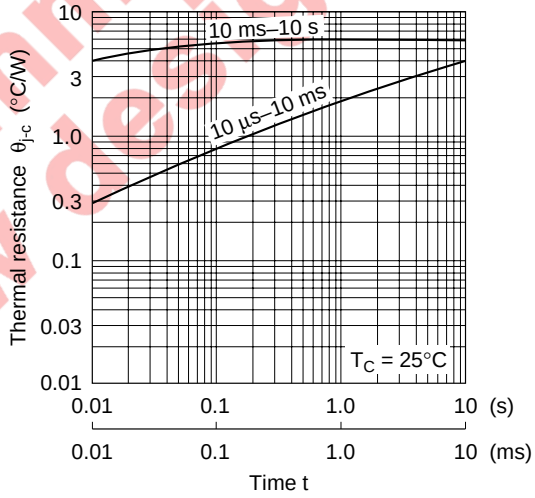
Area of Safe Operation



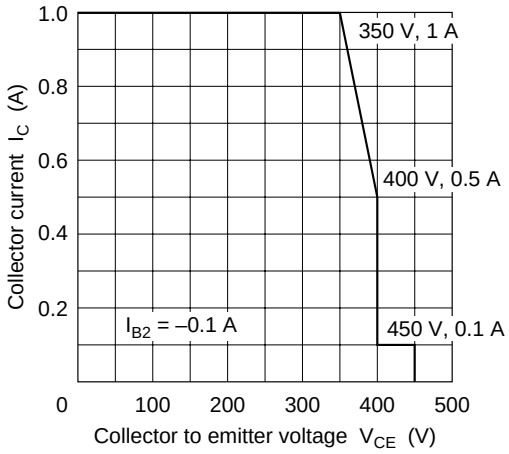
Collector Current Derating Rate



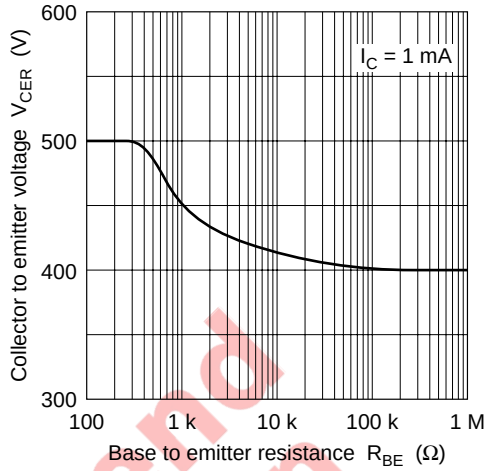
Transient Thermal Resistance



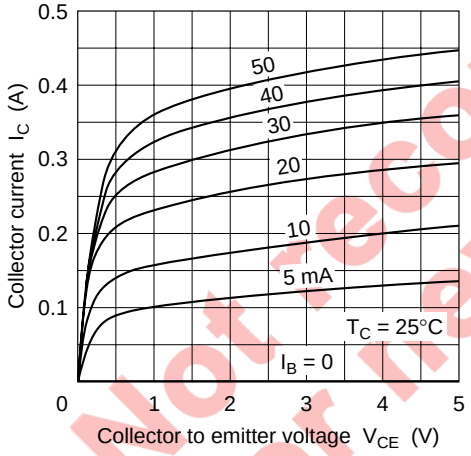
Reverse Bias Area of Safe Operation



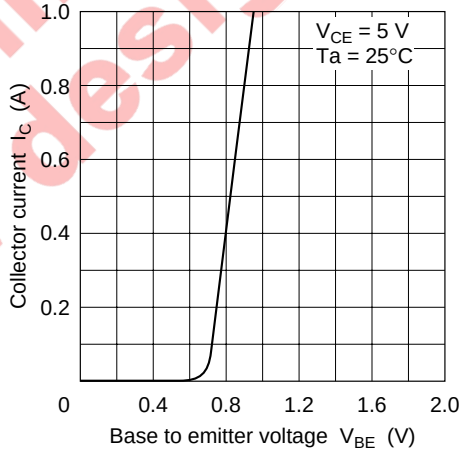
Collector to Emitter Voltage vs. Base to Emitter Resistance



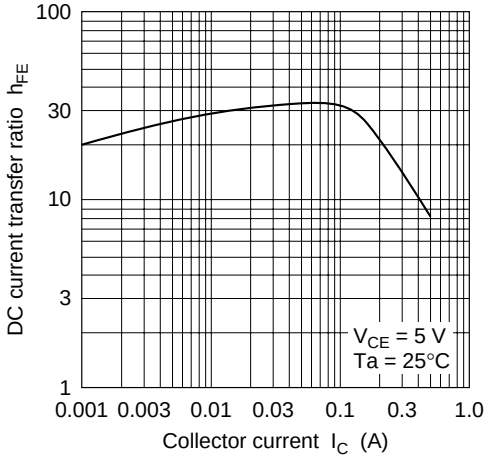
Typical Output Characteristics



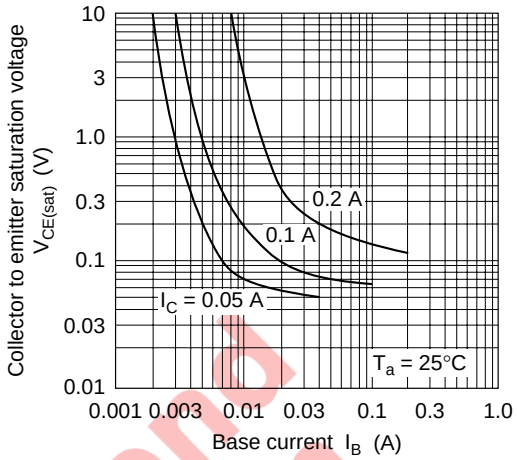
Typical Transfer Characteristics



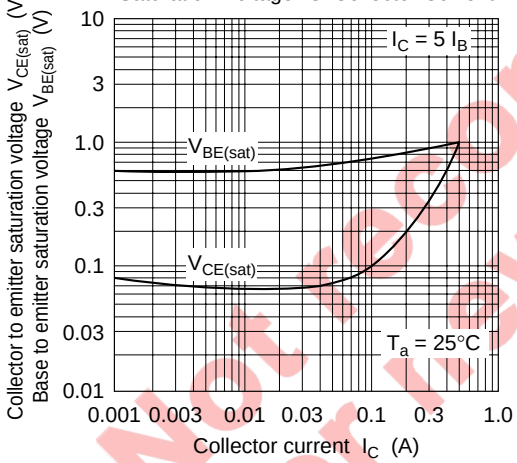
DC Current Transfer Ratio vs. Collector Current



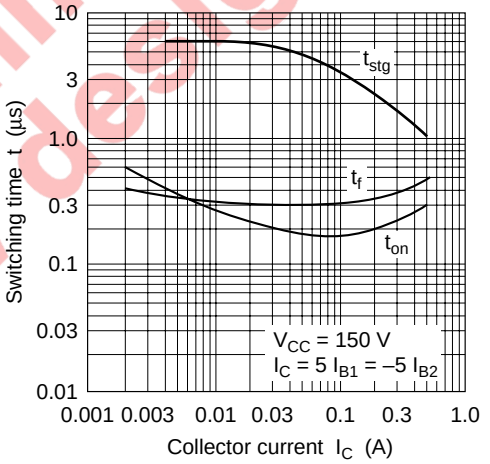
Collector to Emitter Saturation Voltage vs. Base Current

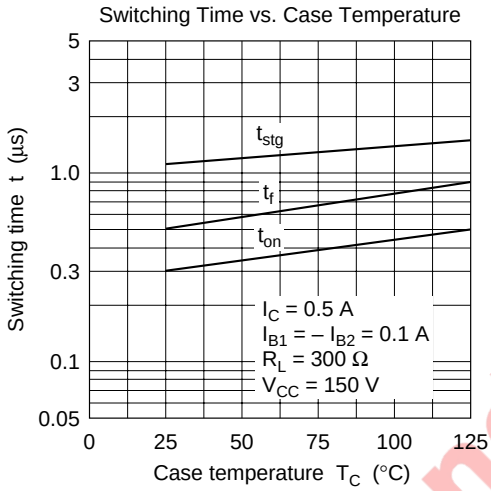


Saturation Voltage vs. Collector Current



Switching Time vs. Collector Current





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HITACHI

Hitachi, Ltd.
Semiconductor & IC Div.
Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100, Japan
Tel: Tokyo (03) 3270-2111
Fax: (03) 3270-5109

For further information write to:

Hitachi America, Ltd.
Semiconductor & IC Div.
2000 Sierra Point Parkway
Brisbane, CA. 94005-1835
U S A
Tel: 415-589-8300
Fax: 415-583-4207

Hitachi Europe GmbH
Electronic Components Group
Continental Europe
Dornacher Straße 3
D-85622 Feldkirchen
München
Tel: 089-9 91 80-0
Fax: 089-9 29 30 00

Hitachi Europe Ltd.
Electronic Components Div.
Northern Europe Headquarters
Whitebrook Park
Lower Cookham Road
Maidenhead
Berkshire SL6 8YA
United Kingdom
Tel: 0628-585000
Fax: 0628-778322

Hitachi Asia Pte. Ltd.
16 Collyer Quay #20-00
Hitachi Tower
Singapore 0104
Tel: 535-2100
Fax: 535-1533

Hitachi Asia (Hong Kong) Ltd.
Unit 706, North Tower,
World Finance Centre,
Harbour City, Canton Road
Tsim Sha Tsui, Kowloon
Hong Kong
Tel: 27359218
Fax: 27306071